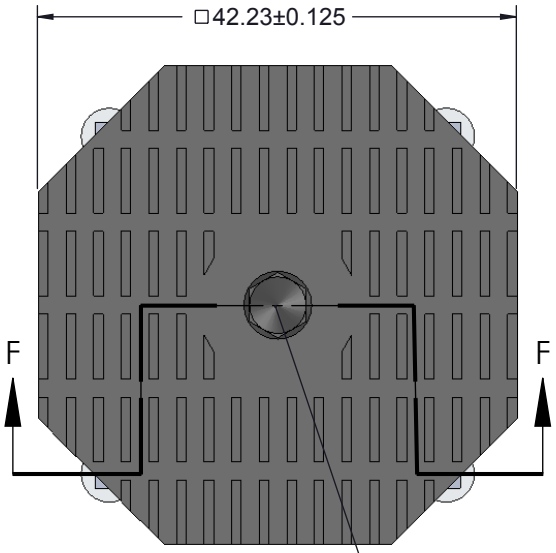
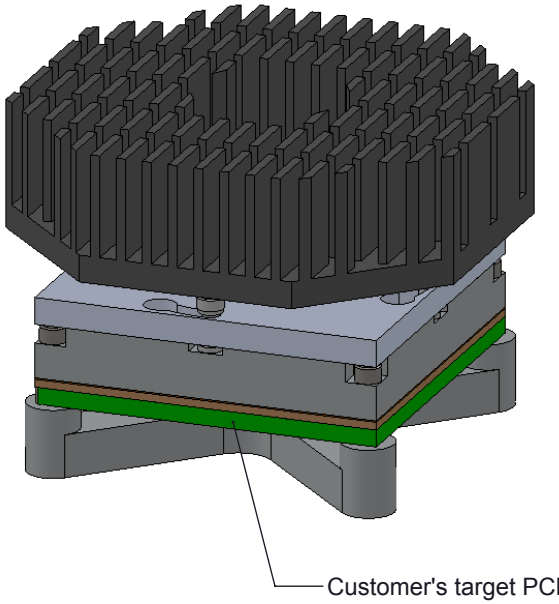
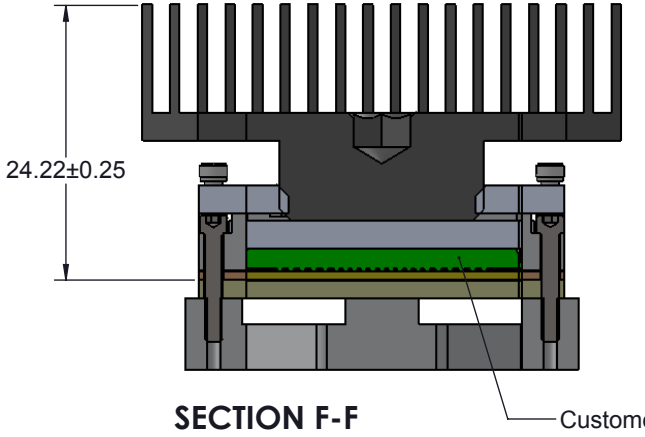
GHz BGA SOCKET - direct mount, solderless

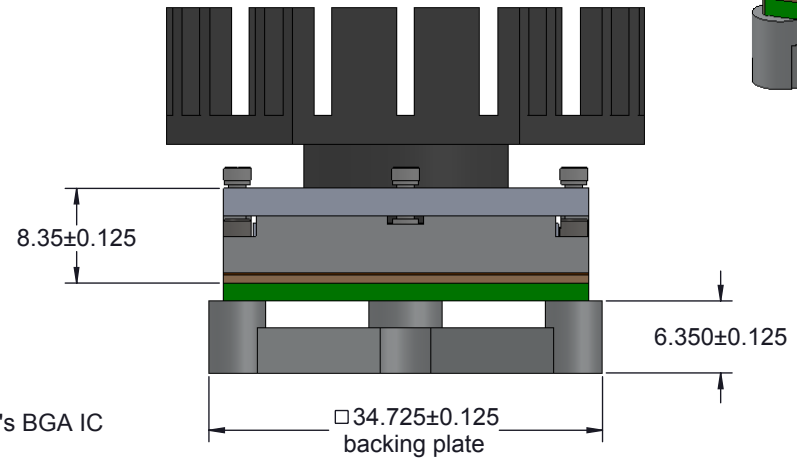


Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- High speed reliable elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid







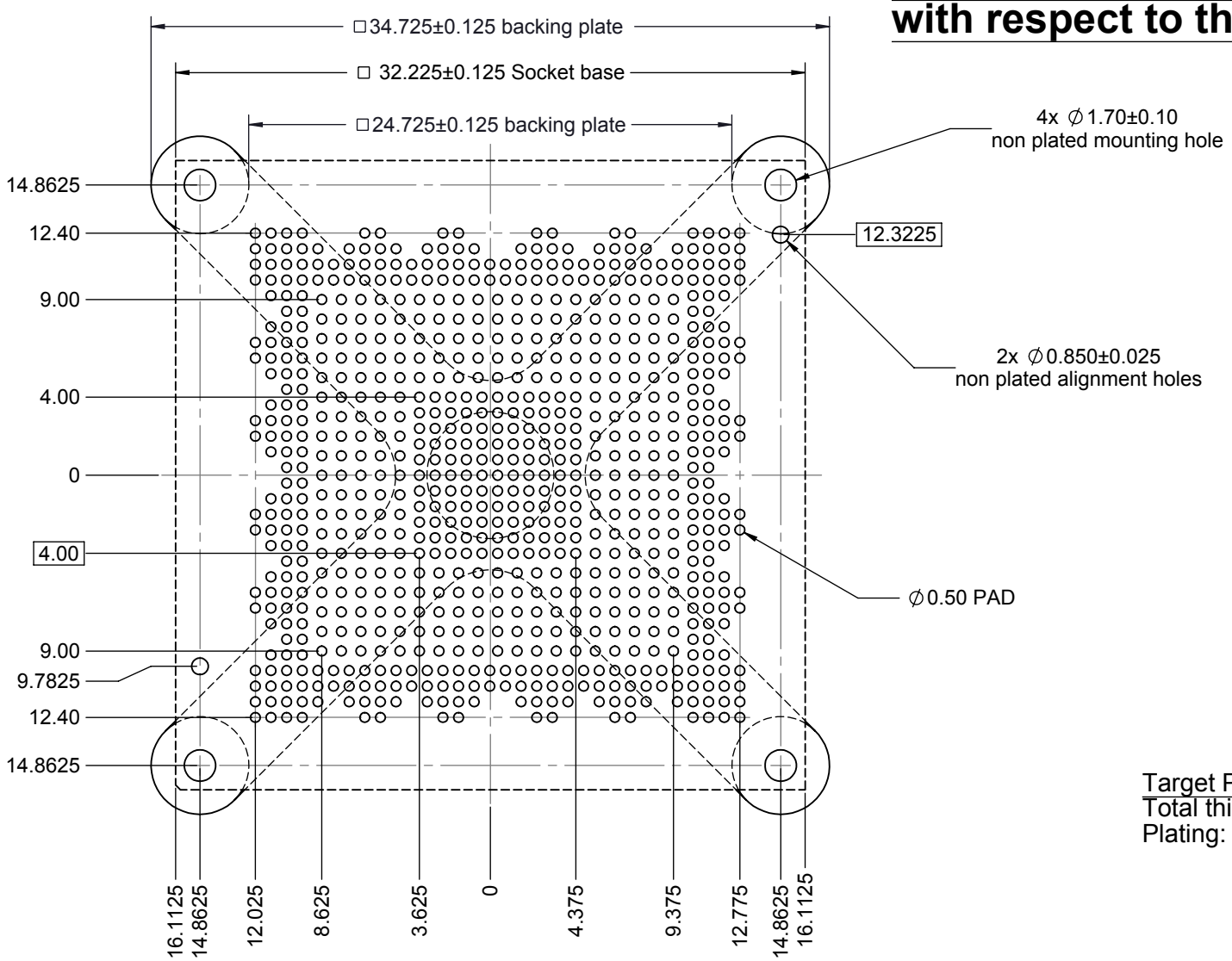
Description: Socket for 27x27mm, 1mm and 0.8mm pitch BGA761

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG-BGA-6353 Drawing		STATUS: Released	SHEET 1 OF 4	REV. C
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT: 51.68 MATERIAL: N/A FINISH: N/A	DRAWN BY: E. Smolentseva	SCALE: 3:2	
		File: SG-BGA-6353 Dwg	DATE: 1/20/2012	

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

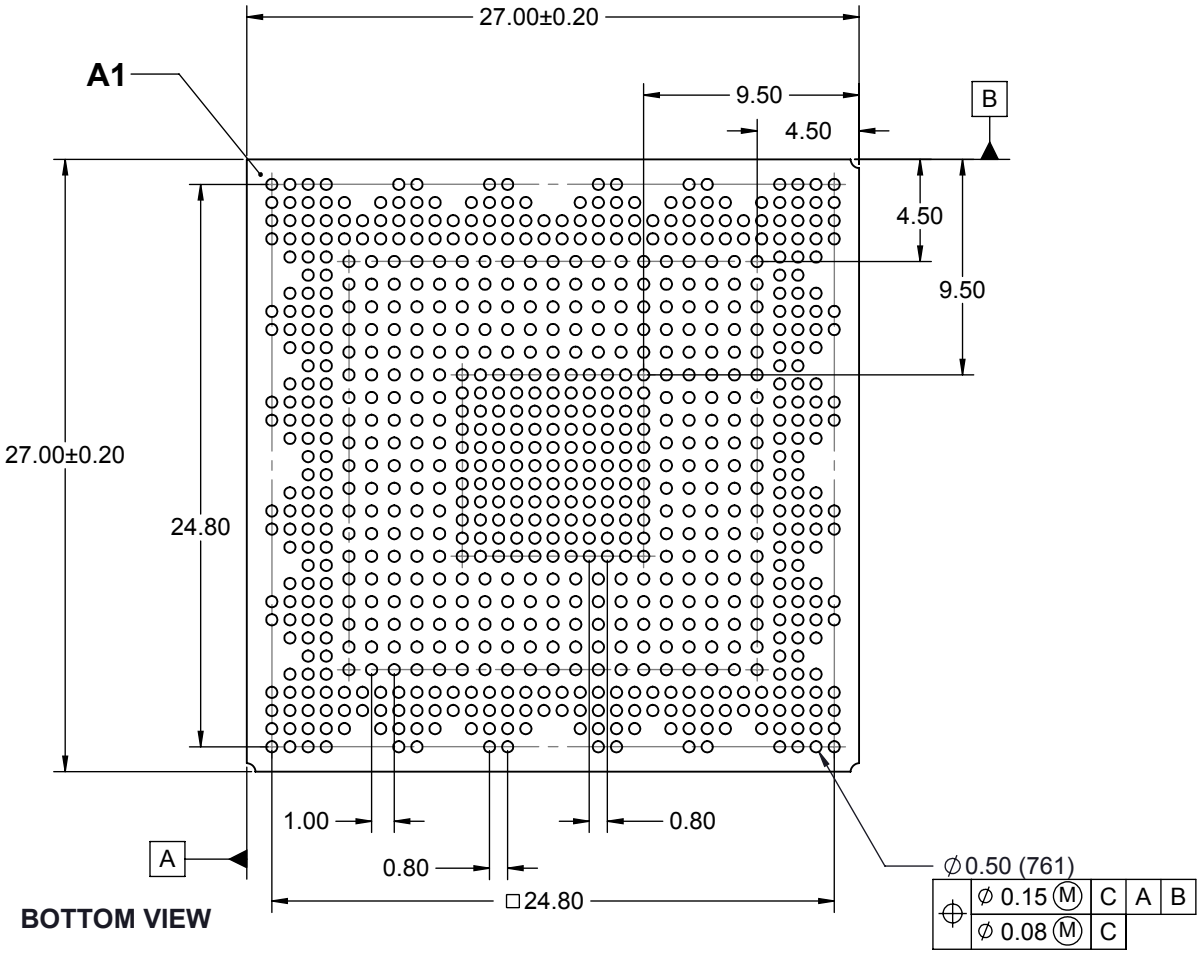


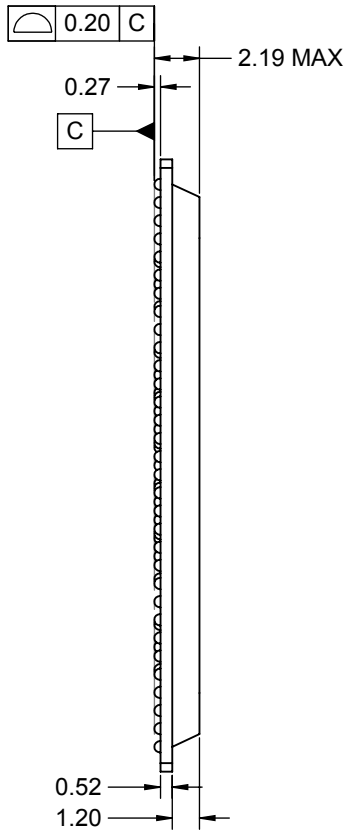
Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

Description: Recommmended PCB layout

Primary dimension units are millimeters, Secondary dimension units are [inches].
Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG-BGA-6353 Drawing		STATUS: Released	SHEET 2 OF 4	REV. C
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT: 51.68 MATERIAL: N/A FINISH: N/A	DRAWN BY: E. Smolentseva	SCALE: 3:1	
		File: SG-BGA-6353 Dwg	DATE: 1/20/2012	





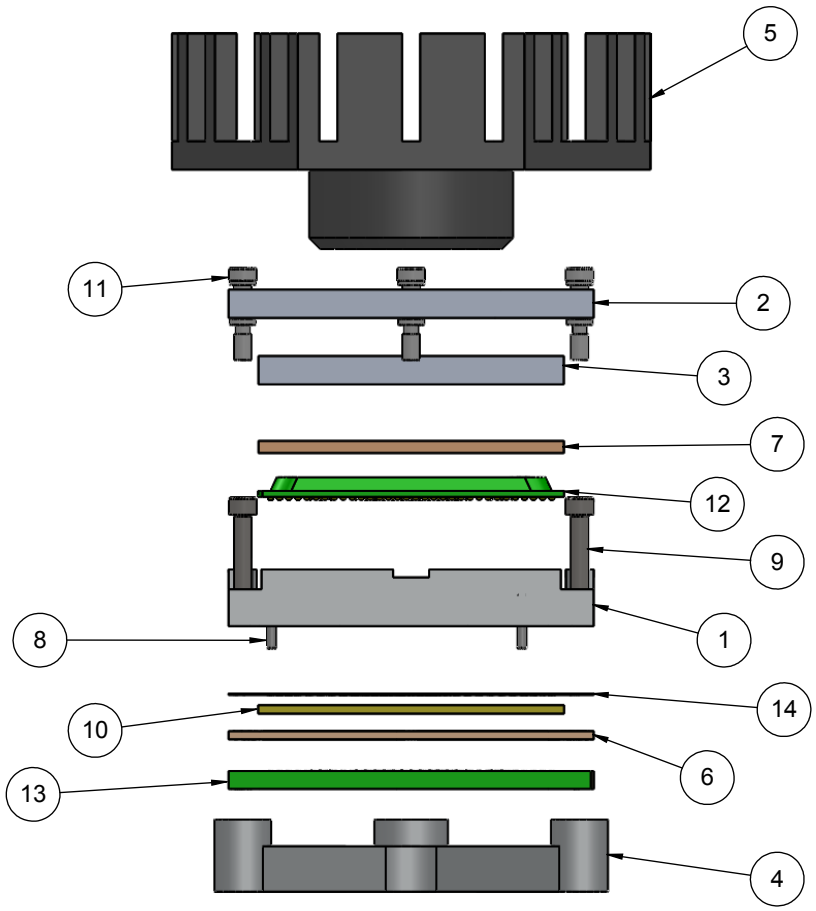
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: Socket for 27x27mm, 1mm and 0.8mm pitch BGA761

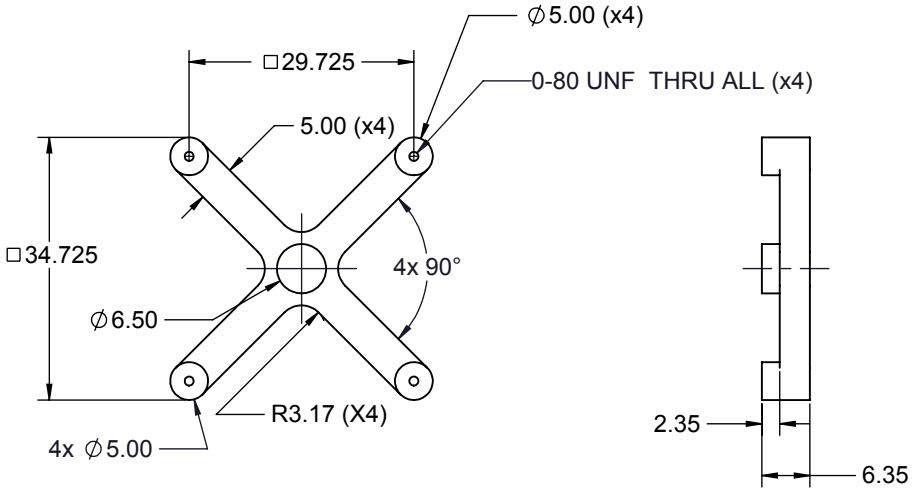
Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG-BGA-6353 Drawing		STATUS: Released	SHEET 3 OF 4	REV. C
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT: 51.68 MATERIAL: N/A FINISH: N/A	DRAWN BY: E. Smolentseva	SCALE: 3:1	
		File: SG-BGA-6353 Dwg	DATE: 1/20/2012	



ITEM NO.	DESCRIPTION	Material
1	Socket Base, 32.225 X 32.225	7075-T6 Aluminum Alloy
2	Socket Lid, 32.225 X 32.225	7075-T6 Aluminum Alloy
3	Compression Plate, 26.95 X 26.95	7075-T6 Aluminum Alloy
4	Backing Plate 27mm IC 5 post	7075-T6 Aluminum Alloy
5	compression screw	7075-T6 Aluminum Alloy
6	Elastomer Guide 27mm IC	Ultem 1000
7	IC Frame	Ultem 1000
8	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
9	#0-80 X .375 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel
10	Elastomer 0.75mm thick 40 Micron gold plated filaments arranged symmetrically in a silicone rubber(63.5 degree angle)	20 Micron dia gold plated brass filaments arranged symettrically in a silicon rubber (63.5 degree angle)
11	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)
12	BGA761 IC 27x27mm 1/0.8mm Pitch	Material <not specified>
13	Customer's target PCB	FR4 Standard
14	Ball guide for 27x27mm 26x26 array 1mm + 0.8mm pitch	Kapton Polyimide/Cirlex



Description: Socket for 27x27mm, 1mm and 0.8mm pitch BGA761

BACKING PLATE

Primary dimension units are millimeters, Secondary dimension units are [inches].
Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG-BGA-6353 Drawing		STATUS: Released	SHEET 4 OF 4	REV. C
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT: 51.68 MATERIAL: N/A FINISH: N/A	DRAWN BY: E. Smolentseva	SCALE: 3:2	
		File: SG-BGA-6353 Dwg	DATE: 1/20/2012	

REV	Requestor	Date	ECO #	Description of Change
B	ELS	1/27/12		1. Centered the inner array inside the outer array
C	ELS	6/12/2	8096G	1. Changed P10724 test chip to P11237.

Description: Modifications

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG-BGA-6353 Specification		STATUS:	SHEET 5 OF 5	REV. C
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Finish: Weight:	DRAWN BY: E. Smolentseva	SCALE: 1:1	
		File: SG-BGA-6353 Dwg	DATE: 1/20/2012	